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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10078718	FILING DATE 02/19/2002	CLASS 439	SUBCLASS 29	GAU 2833	EXAMINER T. J. ...
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**APPLICANTS: Yeo Yong; Khan Navas; Iyer Mahadevan;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 4795-002
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	
Verified and Acknowledged Examiners's initials	
TITLE : Enhanced chip scale package for wire bond dies	

U.S. DEPT. OF COMM /PAT & TM-PTO-436L (Rev 12-94)

NOTICE OF ALLOWANCE MAILED

CLAIMS ALLOWED

Assistant Examiner

Total Claims

Print Claim for
O.G.

ISSUE FEE

DRAWING

Amount Due | Date Paid

Sheets Drwa. | Figs. Drwa. | Print Figs.